

## **AMENDMENTS TO THE SPECIFICATION**

Please replace Paragraph [0046] with the following paragraph rewritten in amendment format:

[0046] In the configuration of the above-described embodiment, the conductive layer 5 directly connects the A1 electrode 2 and the surface of the protrusion 4 and includes a first conductive layer 5a and a second conductive layer 5b. However, indirect connection may be adopted as shown in FIG. 11. Specifically, ~~a~~the first conductive layer 5a is formed in order to cover the A1 electrode 2 before the formation of the resin layer 4a by the above-described manufacturing method and, thereby, the resin layer 4a is formed on regions except for the regions immediately above the A1 electrodes 2. Once the resin layer 4a is formed, the second conductive layer 5b is formed. Examples of methods for manufacturing the first conductive layer 5a include an electroless nickel plating treatment, sputtering, and the like.

Please add the following paragraph after Paragraph [0028].

[0028.1] Fig. 11 is a sectional view of the section indicated by a line B-B shown in Fig. 1 showing a conductive layer comprising a first layer and a second layer.